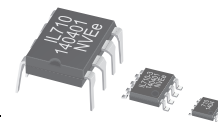
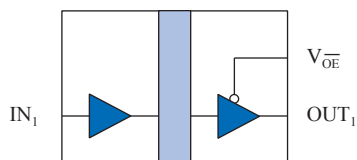


High Speed Digital Isolators



Functional Diagram



IL710

Truth Table

| V_I | V_{OE} | V_O |
|-------|----------|-------|
| L | L | L |
| H | L | H |
| L | H | Z |
| H | H | Z |

Features

- High Speed: 150 Mbps typical (IL710S)
- 3 V to 5.5 V power supplies
- 50 kV/μs typ.; 30 kV/μs min. common mode transient immunity
- No carrier or clock for low EMI emissions and susceptibility
- 1.2 mA/channel typical quiescent current
- 300 ps typical pulse width distortion (IL710S)
- 100 ps pulse jitter
- 2 ns channel-to-channel skew
- 10 ns typical propagation delay
- 600 V_{RMS} working voltage per VDE 0884
- 2500 V_{RMS} isolation voltage per UL 1577
- 44000 year barrier life
- Excellent magnetic immunity
- UL 1577 recognized; IEC 60747-5-5 (VDE 0884) certified
- 8-pin MSOP, SOIC, and PDIP packages

Applications

- Digital Fieldbus
- RS-485 and RS-422
- Ground loop elimination
- Peripheral interfaces
- Serial communication
- Logic level shifting
- Equipment covered under IEC 61010-1 Edition 3
- 5 kV_{RMS} rated IEC 60601-1 medical applications

Description

NVE's IL700 family of high-speed digital isolators are CMOS devices manufactured with NVE's patented* IsoLoop® spintronic Giant Magnetoresistive (GMR) technology. The IL710S is the world's fastest isolator of its type, with a 150 Mbps typical data rate.

A unique ceramic/polymer composite barrier provides excellent isolation and virtually unlimited barrier life.

The symmetric magnetic coupling barrier provides a typical propagation delay of only 10 ns and a pulse width distortion as low as 300 ps (0.3 ns), achieving the best specifications of any isolator. Typical transient immunity of 50 kV/μs is unsurpassed. The IL710 is ideal for isolating applications such as PROFIBUS, RS-485, and RS-422.

The IL710 is available in 8-pin MSOP, SOIC, and PDIP packages. Standard and S-Grade parts are specified over a temperature range of -40°C to +100°C; T-Grade parts are specified over a temperature range of -40°C to +125°C.

Absolute Maximum Ratings

| Parameters | Symbol M | in. | Typ. | Max. | Units | Test Conditions |
|--|--------------------|------|------|-----------------|-------|-----------------|
| Storage Temperature | T_S | -55 | | 150 | °C | |
| Junction Temperature | T_J | -55 | | 150 | °C | |
| Ambient Operating Temperature ⁽¹⁾ IL710T | T_A | -40 | | 100 125 | °C | |
| Supply Voltage | V_{DD1}, V_{DD2} | -0.5 | | 7 | V | |
| Input Voltage | V_I | -0.5 | | $V_{DD1}+0.5$ V | | |
| Input Voltage | V_{OE} | -0.5 | | $V_{DD2}+0.5$ V | | |
| Output Voltage | V_O | -0.5 | | $V_{DD2}+0.5$ V | | |
| Output Current Drive | I_O | | | 10 | mA | |
| Lead Solder Temperature | | | | 260 | °C | 10 sec. |
| ESD | | | 2 | | kV | HBM |

Recommended Operating Conditions

| Parameters | Symbol M | in. | Typ. | Max. | Units | Test Conditions |
|---|--------------------|------------|------|-------------|----------|-----------------|
| Ambient Operating Temperature IL710 and IL710S IL710T | T_A | -40 -40 | | 100 125 | °C °C | |
| Junction Temperature IL710 and IL710S IL710T | T_J | -40 -40 | | 110 125 | °C °C | |
| Supply Voltage | V_{DD1}, V_{DD2} | 3.0 | | 5.5 | V | |
| Logic High Input Voltage | V_{IH} | 2.4 | | V_{DD1} V | | |
| Logic Low Input Voltage | V_{IL} | 0 | | 0.8 | V | |
| Input Signal Rise and Fall Times | t_{IR}, t_{IF} | | | 1 | µs | |

Insulation Specifications

| Parameters | Symbol M | in. | Typ. | Max. | Units | Test Conditions |
|--|----------|----------|------------|------|-----------|---|
| Creepage Distance (external) | | | | | | |
| MSOP | | 3.01 | | | mm | |
| SOIC | | 4.04 | | | mm | |
| PDIP | | 7.04 | | | mm | |
| Total Barrier Thickness (internal) | | | | | | |
| | | 0.012 | 0.013 | | mm | |
| Leakage Current ⁽⁵⁾ | | | 0.2 | | µA | 240 $V_{RMS}, 60$ Hz |
| Barrier Resistance ⁽⁵⁾ | R_{IO} | | $>10^{14}$ | | Ω | 500 V |
| Barrier Capacitance ⁽⁵⁾ | C_{IO} | | 1.1 | | pF | f = 1 MHz |
| Comparative Tracking Index | CTI | ≥175 | | | V | Per IEC 60112 |
| High Voltage Endurance (Maximum Barrier Voltage for Indefinite Life) | AC | V_{IO} | 1000 | | V_{RMS} | At maximum operating temperature |
| | DC | | 1500 | | V_{DC} | |
| Barrier Life | | | 44000 | | Years | 100°C, 1000 $V_{RMS}, 60\%$ CL activation energy |

Thermal Characteristics

| Parameter | Symbol M | in. | Typ. | Max. | Units | Test Conditions |
|---|----------------------|---------------|------|-------------------|-------|---|
| Junction–Ambient Thermal Resistance | MSOP | θ_{JA} | 80 | | °C/W | Soldered to double- sided board; free air |
| | SOIC | | 60 | | | |
| | PDIP | | 60 | | | |
| Junction–Case (Top) Thermal Resistance | MSOP | Ψ_{JT} | 40 | | °C/W | |
| | SOIC | | 10 | | | |
| | PDIP | | 20 | | | |
| Power Dissipation | MSOP SOIC PDIP | P_D | | 500 675 800 | mW | |

Safety and Approvals

IEC 60747-5-5 (VDE 0884) (File Number 5016933-4880-0001)

- Working Voltage (V_{IORM}) 600 V_{RMS} (848 V_{PK}); basic insulation; pollution degree 2
- Transient overvoltage (V_{IOTM}) and surge voltage (V_{IOSM}) 4000 V_{PK}
- Each part tested at 1590 V_{PK} for 1 second, 5 pC partial discharge limit
- Samples tested at 4000 V_{PK} for 60 sec.; then 1358 V_{PK} for 10 sec. with 5 pC partial discharge limit

| Safety-Limiting Values | Symbol | Value | Units |
|--|--------|-------|-------------|
| Safety rating ambient temperature | T_S | 180 | $^{\circ}C$ |
| Safety rating power (180 $^{\circ}C$) | P_S | 270 | mW |
| Supply current safety rating (total of supplies) | I_S | 54 | mA |

IEC 61010-1 (Edition 2; TUV Certificate Numbers N1502812; N1502812-101)

Reinforced Insulation; Pollution Degree II; Material Group III

| Part No. Suffix | Package | Working Voltage |
|-----------------|---------|-----------------|
| -1 | MSOP | 150 V_{RMS} |
| -2 | PDIP | 300 V_{RMS} |
| -3 | SOIC | 150 V_{RMS} |

UL 1577 (Component Recognition Program File Number E207481)

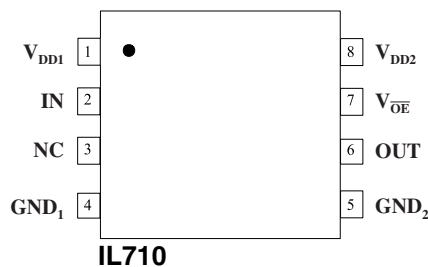
Each part other than MSOP tested at 3000 V_{RMS} (4240 V_{PK}) for 1 second; each lot sample tested at 2500 V_{RMS} (3530 V_{PK}) for 1 minute
MSOP tested at 1200 V_{RMS} (1768 V_{PK}) for 1 second; each lot sample tested at 1200 V_{RMS} (1768 V_{PK}) for 1 minute

Soldering Profile

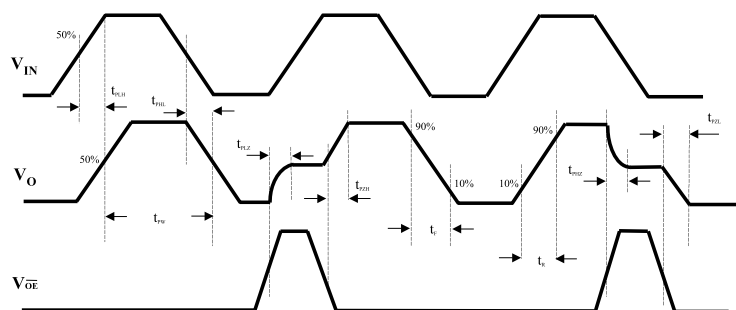
Per JEDEC J-STD-020C, MSL 1

IL710 Pin Connections

| | | |
|---|------------------|---|
| 1 | V _{DD1} | Supply voltage |
| 2 | IN | Data In |
| 3 | NC | No internal connection |
| 4 | GND ₁ | Ground return for V _{DD1} |
| 5 | GND ₂ | Ground return for V _{DD2} |
| 6 | OUT | Data Out |
| 7 | V _{OE} | Output enable. Internally held low with 100 k Ω |
| 8 | V _{DD2} | Supply voltage |



Timing Diagram



Legend

| | |
|-----------|---|
| t_{PLH} | Propagation Delay, Low to High |
| t_{PHL} | Propagation Delay, High to Low |
| t_{PW} | Minimum Pulse Width |
| t_{PLZ} | Propagation Delay, Low to High Impedance |
| t_{PZH} | Propagation Delay, High Impedance to High |
| t_{PHZ} | Propagation Delay, High to High Impedance |
| t_{PZL} | Propagation Delay, High Impedance to Low |
| t_R | Rise Time |
| t_F | Fall Time |

| 3.3 Volt Electrical Specifications (T _{min} to T _{max} unless otherwise stated) | | | | | | |
|---|------------------|------------------------|--------------------------------|------|-------|---|
| Parameters | Symbol | Min. | Typ. | Max. | Units | Test Conditions |
| Input Quiescent Supply Current | I _{DD1} | 8 | | 10 | μA | |
| Output Quiescent Supply Current | I _{DD2} | | 1.2 | 1.75 | mA | |
| Logic Input Current | I _I | -10 | | 10 | μA | |
| Logic High Output Voltage | V _{OH} | V _{DD} -0.1 V | $\frac{DD}{0.9 \times V_{DD}}$ | | V | I _O = -20 μA, V _I = V _{IH} |
| | | 0.8 x V _{DD} | | | | I _O = -4 mA, V _I = V _{IH} |
| Logic Low Output Voltage | V _{OL} | 0 | | 0.1 | V | I _O = 20 μA, V _I = V _{IL} |
| | | | | 0.5 | | 0.8 |

| Switching Specifications (V _{DD} = 3.3 V) | | | | | | |
|---|--|------------|------------|--------|--------------|--|
| Maximum Data Rate IL710 and IL710T IL710S | | 100 130 | 110 140 | | Mbps Mbps | C _L = 15 pF C _L = 15 pF |
| Pulse Width ⁽⁷⁾ | PW | 10 | 7.5 | | ns | 50% Points, V _O |
| Propagation Delay Input to Output (High to Low) | t _{PHL} | | 12 | 18 | ns | C _L = 15 pF |
| Propagation Delay Input to Output (Low to High) | t _{PLH} | | 12 | 18 | ns | C _L = 15 pF |
| Propagation Delay Enable to Output (High to High Impedance) | t _{PHZ} | | 3 | 5 | ns | C _L = 15 pF |
| Propagation Delay Enable to Output (Low to High Impedance) | t _{PLZ} | | 3 | 5 | ns | C _L = 15 pF |
| Propagation Delay Enable to Output (High Impedance to High) | t _{PZH} | | 3 | 5 | ns | C _L = 15 pF |
| Propagation Delay Enable to Output (High Impedance to Low) | t _{PZL} | | 3 | 5 | ns | C _L = 15 pF |
| Pulse Width Distortion ⁽²⁾ IL710 and IL710T IL710S | PWD | | 2 1 | 3 3 | ns | C _L = 15 pF |
| Pulse Jitter ⁽¹⁰⁾ | t _J | | 100 | | ps | C _L = 15 pF |
| Propagation Delay Skew ⁽³⁾ | t _{PSK} | | 4 | 6 | ns | C _L = 15 pF |
| Output Rise Time (10%–90%) | t _R | | 2 | 4 | ns | C _L = 15 pF |
| Output Fall Time (10%–90%) | t _F | | 2 | 4 | ns | C _L = 15 pF |
| Common Mode Transient Immunity (Output Logic High or Logic Low) ⁽⁴⁾ | CM _H , CM _L 30 | | 50 | | kV/μs | V _{CM} = 1500 V _{DC} t _{TRANSIENT} = 25 ns |
| Dynamic Power Consumption ⁽⁶⁾ | | | 140 | 240 | μA/Mbps | |

| Magnetic Field Immunity ⁽⁸⁾ (V _{DD2} = 3V, 3V < V _{DD1} < 5.5V) | | | | | | |
|--|-----------------------|-----------|------|--|-----|----------------------|
| Power Frequency Magnetic Immunity | H _{PF} 1000 | | 1500 | | A/m | 50Hz/60Hz |
| Pulse Magnetic Field Immunity | H _{PM} | 1800 2000 | | | A/m | t _p = 8μs |
| Damped Oscillatory Magnetic Field | H _{OSC} 1800 | | 2000 | | A/m | 0.1Hz – 1MHz |
| Cross-axis Immunity Multiplier ⁽⁹⁾ | K _X | 2.5 | | | | |

| 5 Volt Electrical Specifications (T_{min} to T_{max} unless otherwise stated) | | | | | | |
|--|-----------|-----------------------|---------------------|------|---------------|--|
| Parameters | Symbol | Min. | Typ. | Max. | Units | Test Conditions |
| Input Quiescent Supply Current | I_{DD1} | | 10 | 15 | μA | |
| Output Quiescent Supply Current | I_{DD2} | | 1.8 | 2.5 | mA | |
| Logic Input Current | I_I | -10 | | 10 | μA | |
| Logic High Output Voltage | V_{OH} | $V_{DD}-0.1\text{ V}$ | V_{DD} | | V | $I_O = -20\ \mu\text{A}, V_I = V_{IH}$ |
| | | $0.8 \times V_{DD}$ | $0.9 \times V_{DD}$ | | | $I_O = -4\ \text{mA}, V_I = V_{IH}$ |
| Logic Low Output Voltage | V_{OL} | 0 | | 0.1 | V | $I_O = 20\ \mu\text{A}, V_I = V_{IL}$ |
| | | | 0.5 | 0.8 | | $I_O = 4\ \text{mA}, V_I = V_{IL}$ |

| Switching Specifications ($V_{DD} = 5\text{ V}$) | | | | | | |
|---|------------------|-----|-----|-----|---------------------------|---|
| Maximum Data Rate IL710 and IL710T | | 100 | 110 | | Mbps | $C_L = 15\ \text{pF}$ |
| IL710S | | 130 | 150 | | Mbps | $C_L = 15\ \text{pF}$ |
| Pulse Width ⁽⁷⁾ | PW | 10 | 7.5 | | ns | 50% Points, V_O |
| Propagation Delay Input to Output (High to Low) | t_{PHL} | | 10 | 15 | ns | $C_L = 15\ \text{pF}$ |
| Propagation Delay Input to Output (Low to High) | t_{PLH} | | 10 | 15 | ns | $C_L = 15\ \text{pF}$ |
| Propagation Delay Enable to Output (High to High Impedance) | t_{PHZ} | | 3 | 5 | ns | $C_L = 15\ \text{pF}$ |
| Propagation Delay Enable to Output (Low to High Impedance) | t_{PLZ} | | 3 | 5 | ns | $C_L = 15\ \text{pF}$ |
| Propagation Delay Enable to Output (High Impedance to High) | t_{PZH} | | 3 | 5 | ns | $C_L = 15\ \text{pF}$ |
| Propagation Delay Enable to Output (High Impedance to Low) | t_{PZL} | | 3 | 5 | ns | $C_L = 15\ \text{pF}$ |
| Pulse Width Distortion ⁽²⁾ IL710 and IL710T | PWD | | 2 | 3 | ns | $C_L = 15\ \text{pF}$ |
| IL710S | | | 0.3 | 3 | | |
| Propagation Delay Skew ⁽³⁾ | t_{PSK} | | 4 | 6 | ns | $C_L = 15\ \text{pF}$ |
| Output Rise Time (10%–90%) | t_R | | 1 | 3 | ns | $C_L = 15\ \text{pF}$ |
| Output Fall Time (10%–90%) | t_F | | 1 | 3 | ns | $C_L = 15\ \text{pF}$ |
| Common Mode Transient Immunity (Output Logic High or Logic Low) ⁽⁴⁾ | $ CM_H , CM_L $ | 30 | 50 | | kV/ μs | $V_{CM} = 1500\ \text{V}_{DC}$ $t_{TRANSIENT} = 25\ \text{ns}$ |
| Dynamic Power Consumption ⁽⁶⁾ | | | 200 | 340 | $\mu\text{A}/\text{Mbps}$ | |

| Magnetic Field Immunity ⁽⁸⁾ ($V_{DD2} = 5\text{ V}, 3\text{ V} < V_{DD1} < 5.5\text{ V}$) | | | | | | |
|--|-----------|------|------|--|-----|------------------------|
| Power Frequency Magnetic Immunity | H_{PF} | 2800 | 3500 | | A/m | 50Hz/60Hz |
| Pulse Magnetic Field Immunity | H_{PM} | 4000 | 4500 | | A/m | $t_b = 8\ \mu\text{s}$ |
| Damped Oscillatory Magnetic Field | H_{OSC} | 4000 | 4500 | | A/m | 0.1Hz – 1MHz |
| Cross-axis Immunity Multiplier ⁽⁹⁾ | K_X | 2.5 | | | | |

Notes (apply to both 3.3 V and 5 V specifications):

- Absolute maximum ambient operating temperature means the device will not be damaged if operated under these conditions. It does not guarantee performance.
- PWD is defined as $|t_{PHL} - t_{PLH}|$. %PWD is equal to PWD divided by pulse width.
- t_{PSK} is the magnitude of the worst-case difference in t_{PHL} and/or t_{PLH} between devices at 25°C.
- CM_H is the maximum common mode voltage slew rate that can be sustained while maintaining $V_O > 0.8 V_{DD2}$. CM_L is the maximum common mode input voltage that can be sustained while maintaining $V_O < 0.8\text{ V}$. The common mode voltage slew rates apply to both rising and falling common mode voltage edges.
- Device is considered a two terminal device: pins 1–4 shorted and pins 5–8 shorted.
- Dynamic power consumption is calculated per channel and is supplied by the channel's input side power supply.
- Minimum pulse width is the minimum value at which specified PWD is guaranteed.
- The relevant test and measurement methods are given in the Electromagnetic Compatibility section on p. 7.
- External magnetic field immunity is improved by this factor if the field direction is "end-to-end" rather than to "pin-to-pin" (see diagram on p. 7).
- 66,535-bit pseudo-random binary signal (PRBS) NRZ bit pattern with no more than five consecutive 1s or 0s; 800 ps transition time.

Application Information

Electrostatic Discharge Sensitivity

This product has been tested for electrostatic sensitivity to the limits stated in the specifications. However, NVE recommends that all integrated circuits be handled with appropriate care to avoid damage. Damage caused by inappropriate handling or storage could range from performance degradation to complete failure.

Electromagnetic Compatibility

IsoLoop Isolators have the lowest EMC footprint of any isolation technology. IsoLoop Isolators' Wheatstone bridge configuration and differential magnetic field signaling ensure excellent EMC performance against all relevant standards.

These isolators are fully compliant with generic EMC standards EN50081, EN50082-1 and the umbrella line-voltage standard for Information Technology Equipment (ITE) EN61000. NVE has completed compliance tests in the categories below:

EN50081-1

Residential, Commercial & Light Industrial

Methods EN55022, EN55014

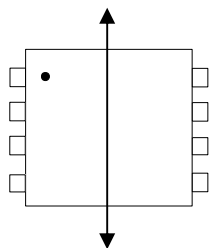
EN50082-2: Industrial Environment

Methods EN61000-4-2 (ESD), EN61000-4-3 (Electromagnetic Field Immunity), EN61000-4-4 (Electrical Transient Immunity), EN61000-4-6 (RFI Immunity), EN61000-4-8 (Power Frequency Magnetic Field Immunity), EN61000-4-9 (Pulsed Magnetic Field), EN61000-4-10 (Damped Oscillatory Magnetic Field)

ENV50204

Radiated Field from Digital Telephones (Immunity Test)

Immunity to external magnetic fields is even higher if the field direction is "end-to-end" rather than to "pin-to-pin" as shown in the diagram below:



Cross-axis Field Direction

Dynamic Power Consumption

IsoLoop Isolators achieve their low power consumption from the way they transmit data across the isolation barrier. By detecting the edge transitions of the input logic signal and converting these to narrow current pulses, a magnetic field is created around the GMR Wheatstone bridge. Depending on the direction of the magnetic field, the bridge causes the output comparator to switch following the input logic signal. Since the current pulses are narrow, about 2.5 ns, the power consumption is independent of mark-to-space ratio and solely dependent on frequency. This has obvious advantages over optocouplers, which have power consumption heavily dependent on mark-to-space ratio.

Power Supply Decoupling

Both power supplies to these devices should be decoupled with low ESR 47 nF ceramic capacitors. Ground planes for both GND₁ and GND₂ are highly recommended for data rates above 10 Mbps. Capacitors must be located as close as possible to the V_{DD} pins.

Signal Status on Start-up and Shut Down

To minimize power dissipation, input signals are differentiated and then latched on the output side of the isolation barrier to reconstruct the signal. This could result in an ambiguous output state depending on power up, shutdown and power loss sequencing. Therefore, the designer should consider including an initialization signal in the start-up circuit. Initialization consists of toggling the input either high then low, or low then high.

Data Transmission Rates

The reliability of a transmission system is directly related to the accuracy and quality of the transmitted digital information. For a digital system, those parameters which determine the limits of the data transmission are pulse width distortion and propagation delay skew.

Propagation delay is the time taken for the signal to travel through the device. This is usually different when sending a low-to-high than when sending a high-to-low signal. This difference, or error, is called pulse width distortion (PWD) and is usually in nanoseconds. It may also be expressed as a percentage:

$$\text{PWD}\% = \frac{\text{Maximum Pulse Width Distortion (ns)}}{\text{Signal Pulse Width (ns)}} \times 100\%$$

For example, with data rates of 12.5 Mbps:

$$\text{PWD}\% = \frac{3 \text{ ns}}{80 \text{ ns}} \times 100\% = 3.75\%$$

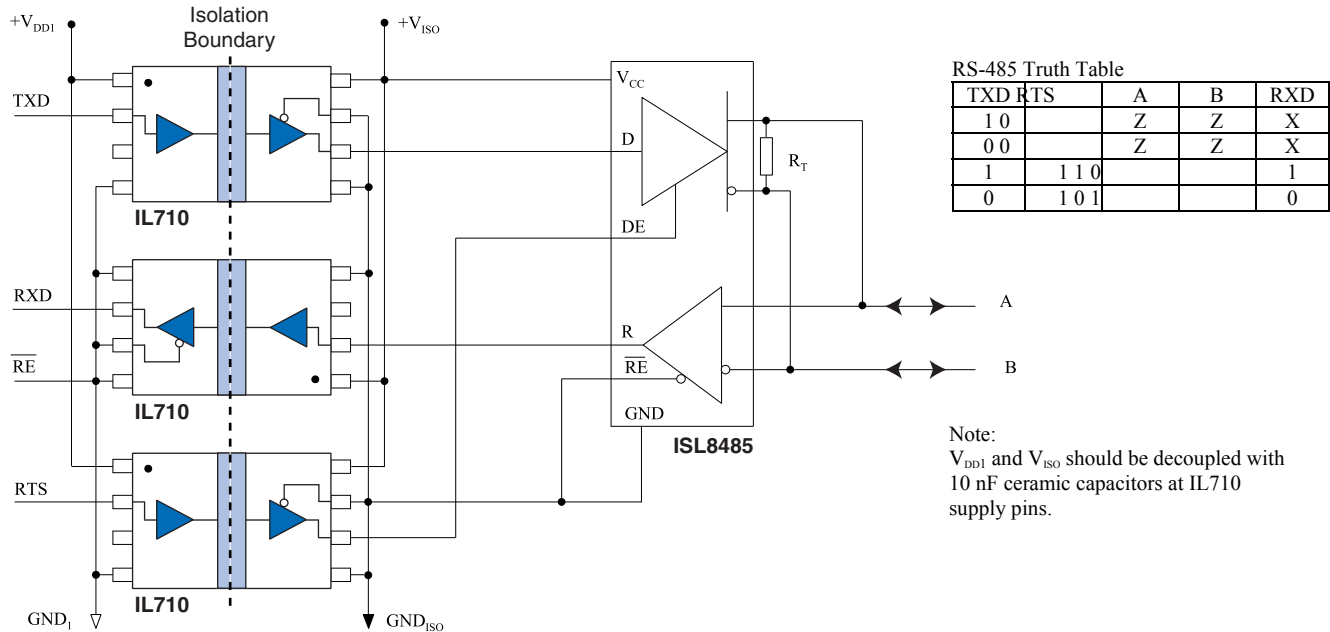
This figure is almost **three times** better than any available optocoupler with the same temperature range, and **two times** better than any optocoupler regardless of published temperature range. IsoLoop isolators exceed the 10% maximum PWD recommended by PROFIBUS, and will run to nearly 35 Mb within the 10% limit.

Propagation delay skew is the signal propagation difference between two or more channels. This becomes significant in clocked systems because it is undesirable for the clock pulse to arrive before the data has settled. Short propagation delay skew is therefore especially critical in high data rate parallel systems for establishing and maintaining accuracy and repeatability. Worst-case channel-to-channel skew in an IL700 Isolator is only 3 ns, which is **ten times** better than any optocoupler. IL700 Isolators have a maximum propagation delay skew of 6 ns, which is **five times** better than any optocoupler.

Application Diagrams

Isolated PROFIBUS / RS-485

NVE offers a unique line of single-chip isolated PROFIBUS/RS-485 transceivers, but as this circuit illustrates, IL710 isolators can also be used as part of multi-chip designs using non-isolated PROFIBUS transceivers:

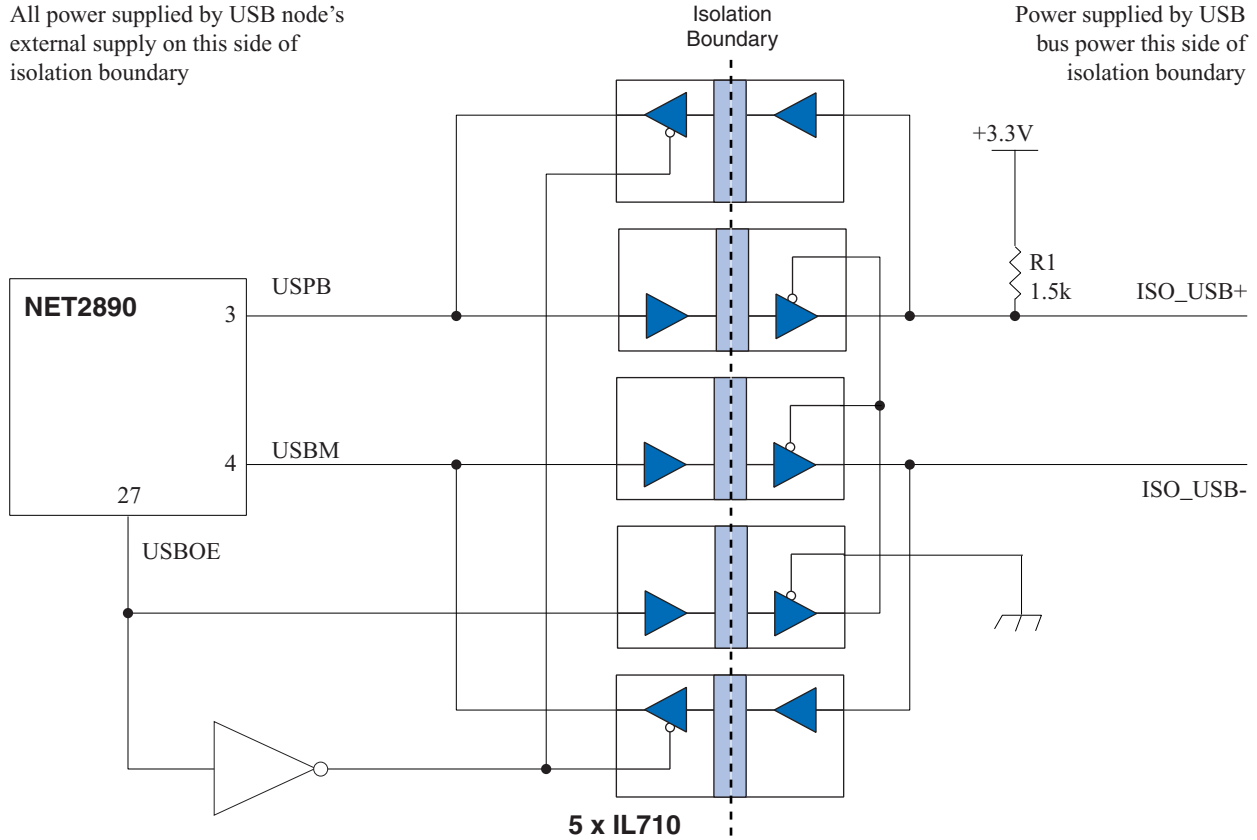


Isolated USB

In this circuit, power is supplied by USB bus power on one side of the isolation barrier, and the USB node's external supply on the other side of the barrier. IL700 Isolators are specified with just 3 ns worst-case pulse width distortion:

All power supplied by USB node's external supply on this side of isolation boundary

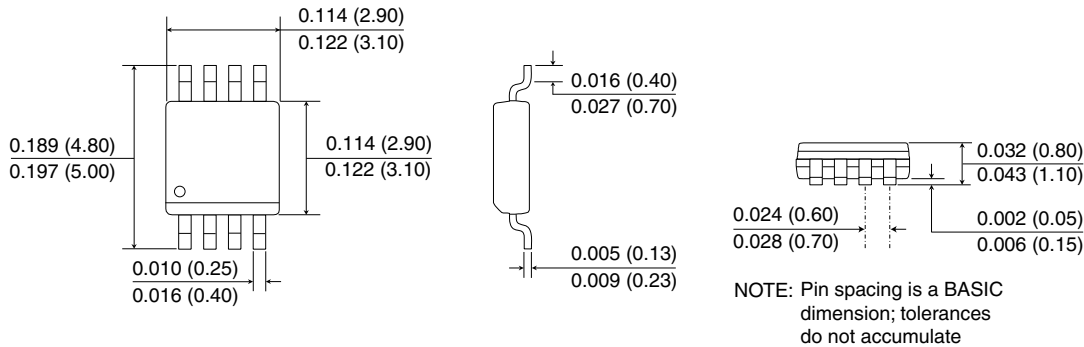
Power supplied by USB bus power this side of isolation boundary



Package Drawings

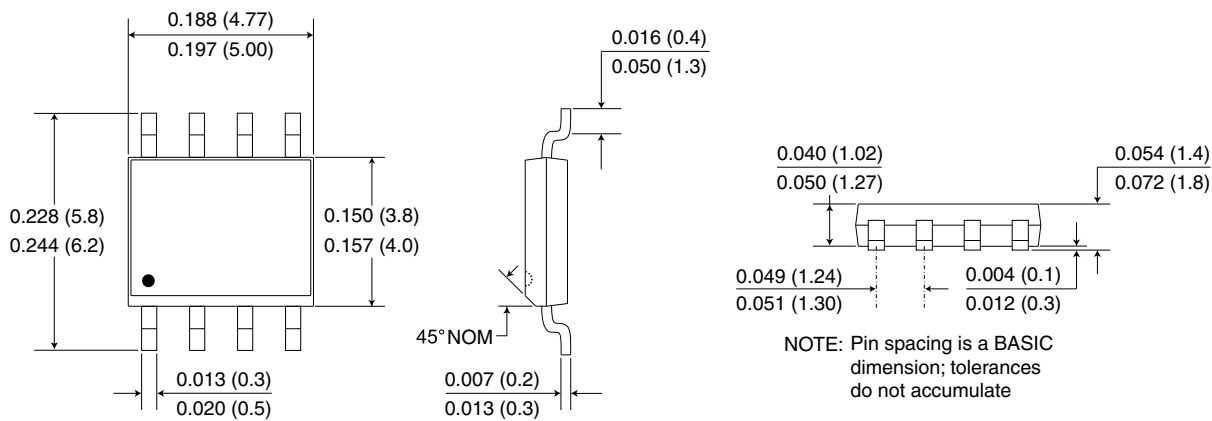
8-pin MSOP (-1 suffix)

Dimensions in inches (mm); scale = approx. 5X



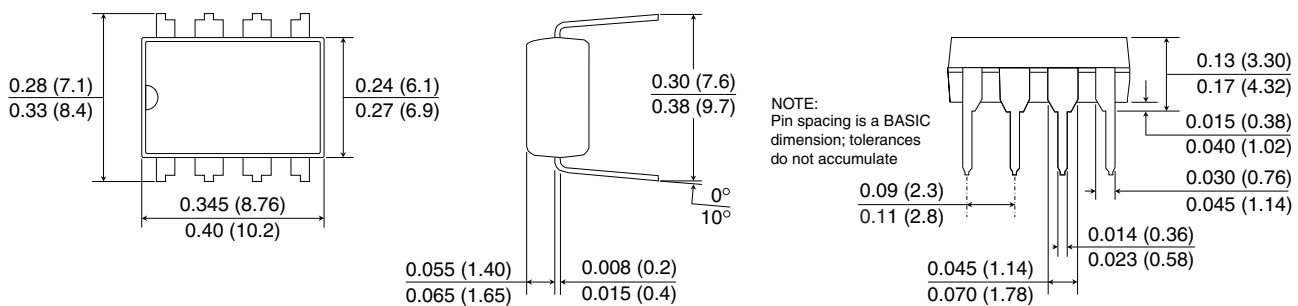
8-pin SOIC Package (-3 suffix)

Dimensions in inches (mm); scale = approx. 5X



8-pin PDIP (-2 suffix)

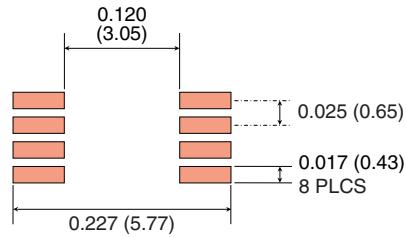
Dimensions in inches (mm); scale = approx. 2.5X



Recommended Pad Layouts

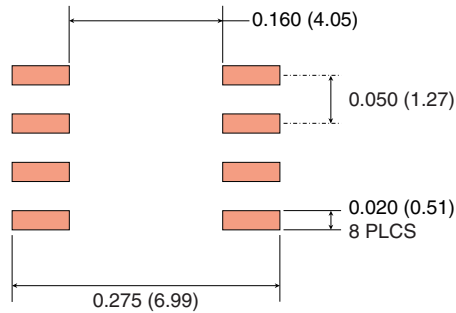
8-pin MSOP Pad Layout

Dimensions in inches (mm); scale = approx. 5X



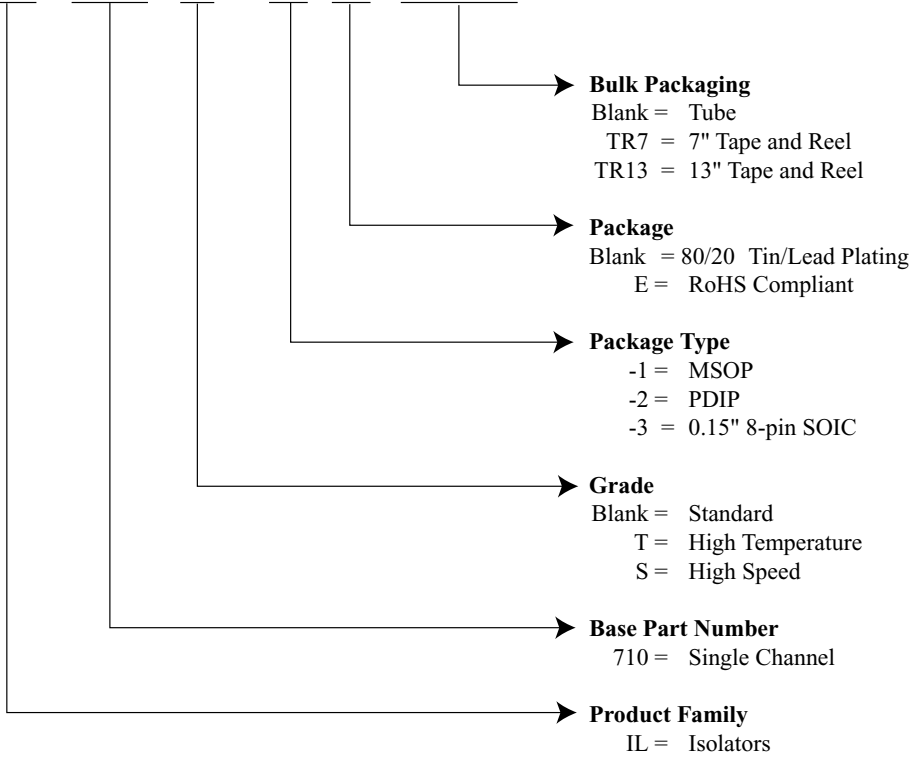
8-pin SOIC Pad Layout

Dimensions in inches (mm); scale = approx. 5X



Ordering Information and Valid Part Numbers

IL 710 T - 3 E TR13



Valid Part Numbers

IL710-1E
IL710S-1E
IL710T-1E

IL710-2
IL710T-2
IL710-2E
IL710T-2E

IL710-3
IL710S-3
IL710T-3
IL710-3E
IL710S-3E
IL710T-3E

All MSOP and SOIC parts are available on tape and reel.



ISB-DS-001-IL710-AC
March 2014

Changes

- Added product illustrations to first page.
- Revised and added details to thermal specifications (p. 2).
- Added VDE 0884 Safety-Limiting Values (p. 3).

ISB-DS-001-IL710-AB

Changes

- IEC 60747-5-5 (VDE 0884) certification.

ISB-DS-001-IL710-AA

Changes

- Tighter quiescent current specifications.
- Upgraded from MSL 2 to MSL 1.

ISB-DS-001-IL710-Z Chan

ges

- Increased transient immunity specifications based on additional data.
- Added VDE 0884 pending.
- Added high voltage endurance specification.
- Increased magnetic immunity specifications.
- Updated package drawings.
- Added recommended solder pad layouts.

ISB-DS-001-IL710-Y

Changes

- Detailed isolation and barrier specifications.
- Cosmetic changes.

ISB-DS-001-IL710-X

Changes

- Tightened typ. output quiescent supply spec. from 1.7 mA to 1.5 mA.
- T-Series quiescent supply specs. tightened to be the same as other grades.

ISB-DS-001-IL710-W

Changes

- Update terms and conditions.

ISB-DS-001-IL710-V

Changes

- Additional changes to MSOP pin spacing on package drawing.

ISB-DS-001-IL710-U

Changes

- Changed MSOP pin spacing on package drawing.

ISB-DS-001-IL710-T Chan

ges

- Added typical jitter specification at 5V.

ISB-DS-001-IL710-S

Changes

- Added EMC details.

ISB-DS-001-IL710-R Chan

ges

- IEC 61010 approval for MSOP version.

ISB-DS-001-IL710-Q

Changes

- Added magnetic immunity to 3.3 and 5 volt electrical specifications.
- Added diagram showing cross-axis direction.
- Added magnetic compatibility to the applications information section.

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ISB-DS-001-IL710-AC

March 2014